

ES1AF THRU ES1JF

Surface Mount Superfast Recovery Rectifier

Reverse Voltage – 50 to 600 V

Forward Current - 1 A

FEATURES

• For surface mounted applications

• Low profile package

• Glass Passivated Chip Juntion

• Superfast reverse recovery time

• Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

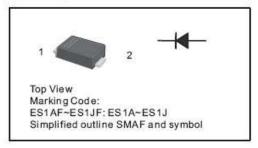
• Case: SMAF

• Terminals: Solderable per MIL-STD-750, Method 2026

• pprox. Weight: 27mg 0.00086oz

PINNING

PIN	PIN DESCRIPTION			
1	Cathode			
2	Anode			



Absolute Maximum Ratings and Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbols	E\$1AF	ES1BF	ES1CF	ES1DF	ES1EF	ES1GF	ES1JF	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	150	200	300	400	600	٧
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V _{DC}	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at T _L = 100 °C	I _{F(AV)}	1						А	
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	25						А	
Maximum Forward Voltage at 1 A	V _F	1 1.25 1.7				1.7	V		
Maximum DC Reverse Current Ta = 25 °C at Rated DC Blocking Voltage Ta = 125 °C	I _R	5 100						μA	
Typical Junction Capacitance at V _R =4V, f=1MHz	Cj	10						pF	
Maximum Reverse Recovery Time at I_F =0.5A, I_R =1A, I_{rr} =0.25A	t _{rr}	35						ns	
Operating and Storage Temperature Range	Tj, Tstg	-55 ~ +150							°C

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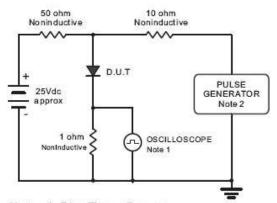
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Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max. Input Impedance = 1megohm, 22pF.

Ries Time =10ns, max.Source Impedance = 50 ohms.

Fig.2 Maximum Average Forward Current Rating

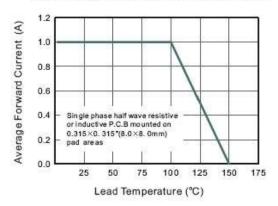
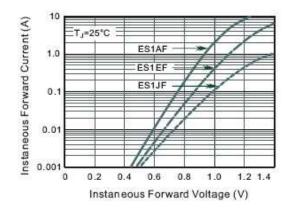


Fig. 4 Typical Forward Characteristics



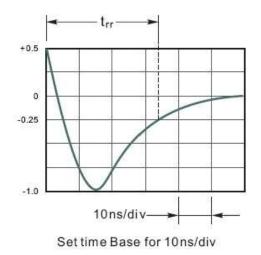


Fig.3 Typical Reverse Characteristics

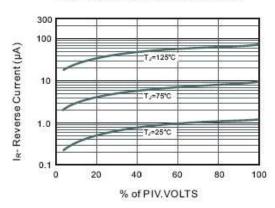
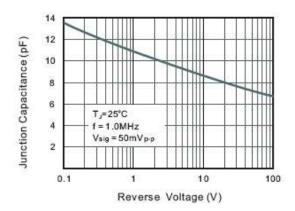


Fig.5 Typical Junction Capacitance



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REV.07

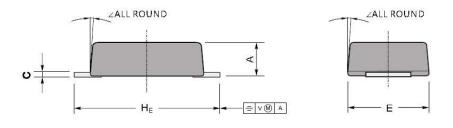


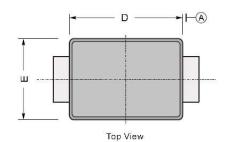
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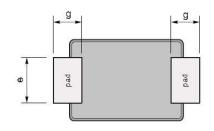
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMAF



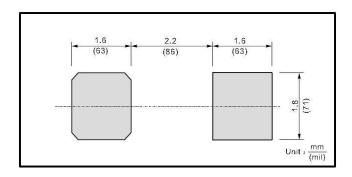




Bottom View

UNIT		Α	С	D	Е	е	g	HE	2
mm	max	1.1	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	8.0	4.4	
mil	max	43	7.9	146	106	63	47	193	(
	min	35	4.7	130	94	51	31	173	

The recommended mounting pad size



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